PRODUCT DATA SHEET
SikaBond®-T55 (J)

LOW VISCOSITY (EASY FLOWING) ELASTIC ADHESIVE FOR WOOD FLOORING

PRODUCT DESCRIPTION

SikaBond-T55 (J) is a one-part elastic adhesive.

USES

With Sikabond-T55 (J):

- Solid and engineered wood floors (strips, longstrips, planks, panels, boards) mosaic parquet, industrial parquet, wood paving (residential) as well as chipboards can be bonded.

CHARACTERISTICS / ADVANTAGES

- One-component, ready to use
- Fast curing
- Elastic, footfall-sound-dampening adhesive
- Suitable for common types of wood floors
- Especially for problematic wood such as beech and bamboo
- Suitable for bonding wood floors directly onto old ceramic tiles
- Reduces stress on the substrate: the elastic, material-compatible adhesive reduces transverse stress between the wood floor and the substrate
- Compensation of small substrate unevenness
- Suitable for subfloor heating

PRODUCT DATA

FORM

COLOUR

Ochre

PACKAGING

2kg sausage, (9 sausages per carton)

STORAGE

STORAGE CONDITIONS / SHELF-LIFE

Twelve (12) months from date of production when stored in undamaged original sealed packaging in dry conditions and protected from direct sunlight at temperatures between +10°C and +25°C.

TECHNICAL DATA

CHEMICAL BASE

One-component, moisture-curing polyurethane

DENSITY

1.34kg/litre

SKINNING / LAYING TIME

~ 45 - 60 minutes (+23°c / 50% r.h.)

CURING RATE

~ 4.0 mm / 24h (+23°C / 50% r.h.)
Floor may be walked on/sanded 12 - 24 hours after installation (depending on climatic conditions and adhesive layer thickness).

SAG FLOW

Spreads easily, trowel marks stable

SERVICE TEMPERATURE

-40°C to +70°C

MECHANICAL / PHYSICAL PROPERTIES

SHEAR STRENGTH

~ 1.0 N/mm^2, 1mm adhesive thickness (+23°C / 50% r.h.) DIN 281

TENSILE STRENGTH

~ 1.5 N/mm^2 (+23°C / 50% r.h.) DIN 53 504

SHORE A HARDNESS

~ 35 (after 28 days) DIN 53 505

ELONGATION AT BREAK

~ 400% (+23°C / 50% r.h.) DIN 53 504

System Information

APPLICATION DETAILS

ADHESIVE CONSUMPTION

Full Surface Bonding:

- 700 - 900g/m^2 with notched trowel B3 (acc. To IVK guidelines) or 3/16” 1/8” 1/8” (engineered strips / planks, mosaic parquet).
- 800 - 1000g/m^2 with notched trowel B11 (acc. To IVK guidelines) AP 48 or 3/16” 3/16” 3/16” (solid wood, engineered longstrips / panels, industrial parquet, wood paving (residential), chipboards).

For bonding of long, wide boards or in case of uneven substrate it could be necessary to use a notched trowel with bigger notches (to avoid hollow sections).
For substrates prepared with Sika Primer MB, the consumption of SikaBond-T55 (J) is lower.

SUBSTRATE QUALITY

- Substrates must be clean, dry, homogeneous, even, and free from grease, dust and loose particles.
- Paint, laitance and other poorly adhering particles must be removed.
- Standard construction rules must be observed.

SUBSTRATE PREPARATION

Concrete / Cement Screed

- Must be ground and thoroughly cleaned with an industrial vacuum cleaner.

Glazed Ceramic and Old Ceramic Tiles

- Degrease, clean with Sika Cleaner-205 or grind the tile surface and clean thoroughly with an industrial vacuum cleaner.

Wood / Gypsum Boards (e.g. Chipboards, Plywood)

- The sheets have to be fixed to the substrate by gluing/screwing.

Unknown Substrates

  - Please contact our technical department.

SikaBond-T55 (J) can be used without priming on cement floors, chipboards, concrete and ceramic tiles.

For cement floors with an excessive moisture content, substrates with residues of previous adhesives and on structurally weak substrates use Sika Primer MB. For detailed instructions consult the Product Data Sheet for Sika Primer MB or contact our Technical Department.

APPLICATION CONDITIONS / LIMITATIONS

SUBSTRATE TEMPERATURES

During laying and until SikaBond-T55 (J) has fully cured, substrate temperature must be > +15°C and in case of floor heating < +20°C.

AMBIENT TEMPERATURE

Room temperature between +15°C and +35°C.

SUBSTRATE HUMIDITY

Permissible substrate moisture content

- 2.5% CM for cement screed (ca. 4% Tramex / Gravimetric weight percent)
- 0.5% CM for anhydrite screed
- 3-12% CM for magnesia flooring (proportion of organic parts)

Permissible substrate moisture content in case of floor heating

- 1.8% CM for cement screed (ca. 3% Tramex / Gravimetric weight percent)
- 0.3% CM for anhydrite screed
- 3-12% CM for magnesia flooring (proportion of organic parts)

For moisture content and quality of substrates the guidelines of the wood floor manufacturer as well as standard construction rules must be observed.

RELATIVE AIR HUMIDITY

Between 40% and 70%.

APPLICATION INSTRUCTIONS

APPLICATION METHOD / TOOLS

Full Surface Bonding:

- SikaBond-T55 (J) is applied to the properly prepared substrate directly from the sausage and uniformly distributed by notched trowel. Press the wood floor elements firmly into the adhesive so that the underside is fully wetted. The elements can then be pressed firmly together using a hammer and an impact block. A gap of 10mm from the wall to the wood floor is required.
- Fresh, uncured adhesive remaining on the wood floor surface must be removed immediately with a clean cloth and if necessary cleaned with Sika Remover-208. Test wood floor surfaces for compatibility with Sika Cleaner-208 before use.
- The laying instructions of the wood floor manufacturer as well as standard construction rules must be observed.

CLEANING OF TOOLS

Clean all tools and application equipment with Sika Remover-208 immediately after use. Hardened / cured material can only be removed mechanically.

POT LIFE

~ 45 minutes

NOTES ON APPLICATION / LIMITATIONS

- Sikafloor-T55 (J) must only be used by experienced applicators.
- The substrate temperature and air temperature limitations detailed above may be varied in accordance with the written recommendations of the supplier of the timber flooring, however SikaBond-T55(J) shall only be used at temperatures between +5°C and +35°C.
- For better workability the adhesive temperature must be at least +15°C.
- For the proper curing of the adhesive sufficient ambient moisture is necessary.
- Wood floor installation in areas without a damp proof membrane can only be undertaken with moisture regulator Sikafloor-EpoCem and Sika Primer MB as a vapour barrier. For detailed instructions consult the Product Data Sheets or contact our Technical Service Department.
- In case of chemically pre-treated types of wood floors (e.g. ammonia, wood stain, timber preservative) and woods with high oil content SikaBond-T55 (J) is only to be used after a written recommendation from out Technical Department.
- Do not use on PE, PP, Teflon, and certain plasticized synthetic materials (carry out pre-trials or contact our Technical Department).

VALUE BASE

All technical data stated in this Product Data Sheet are based on laboratory tests. Actual measured data may vary due to circumstances beyond our control.

LOCAL RESTRICTIONS

Please note that as a result of specific local regulations the performance of this product may vary from country to country. Please consult the local Product Data Sheet for the exact description of the application fields.

HEALTH AND SAFETY INFORMATION

SAFETY PRECAUTIONS

- To avoid rare allergic reactions, we recommend the use of protective gloves. Change soiled work clothes and wash hands before breaks and after finishing work.
- Local regulations as well as health and safety advice on packaging labels must be observed.
- For further information refer to the Sika Safety Data Sheet which is available on request.

IMPORTANT NOTES

- Residues of material must be removed according to local regulations. Fully cured material can be disposed of as household waste under agreement with the responsible local authorities.
- Detailed health and safety information as well as detailed precautionary measures e.g. physical, toxicological and ecological data can be obtained from the safety data sheet.

TRANSPORT

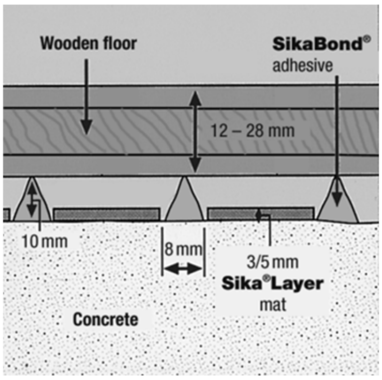
SikaBond T55 (J) is classed as non-hazardous for transportation.

LEGAL NOTES

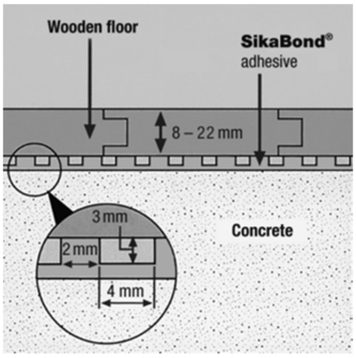
The information, and, in particular, the recommendations relating to the application and end-use of Sika products, are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. In practice, the differences in materials, substrates and actual site conditions are such that no warranty in respect of merchantability or of fitness for a particular purpose, nor any liability arising out of any legal relationship whatsoever, can be inferred either from this information, or from any written recommendations, or from any other advice offered. The user of the product must test the product's suitability for the intended application and purpose. Sika reserves the right to change the properties of its products. The proprietary rights of third parties must be observed. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

SYSTEM DETAILS

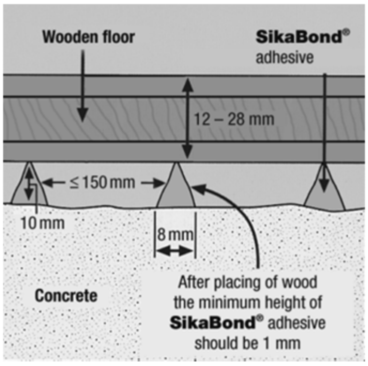
Sika AcouBond System: SikaBond-T53, Sika Layer-05



Full Surface Bonding: SikaBond-T55 (J)



Cordon Application: SikaBond-T53



FOR MORE SIKABOND®-T55 (J) INFORMATION:

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